Unit: mm

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSⅢ)

# **TPCA8102**

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance: RDS (ON) =  $4.5 \text{m}\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 60S$  (typ.)
- Low leakage current:  $I_{DSS} = -10 \mu A (max) (V_{DS} = -30 V)$
- Enhancement mode:  $V_{th} = -0.8 \text{ to } -2.0 \text{ V (V}_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA})$

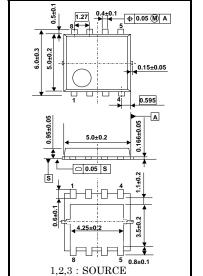
#### Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-30	V	
Drain-gate voltage (R	$k_{GS} = 20 \text{ k}\Omega$	$V_{DGR}$	-30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	<b>- 40</b>	Α	
Diam current	Pulsed (Note 1)	$I_{DP}$	-120	^	
Drain power dissipati	on (Tc=25°C)	$P_{D}$	45	W	
Drain power dissipation	on (t = 10 s) (Note 2a)	$P_{D}$	2.8	W	
Drain power dissipation	on (t = 10 s) (Note 2b)	$P_{D}$	1.6	W	
Single pulse avalanch	ne energy (Note 3)	EAS	208	mJ	
Avalanche current		I <sub>AR</sub>	- 40	Α	
Repetitive avalanche	energy c=25°C) (Note 4)	E <sub>AR</sub>	4.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	-55 to 150	°C	

Note: For (Note 1), (Note 2), (Note 3), (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.

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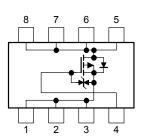


Weight: 0.076 g (typ.)

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4 : GATE 5,6,7,8 : DRAIN

#### **Circuit Configuration**

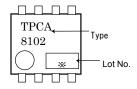


2-5Q1A

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25°C)	R <sub>th (ch-c)</sub>	2.78	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	44.6	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	78.1	°C/W

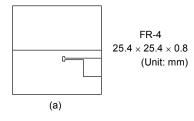
### Marking (Note 5)

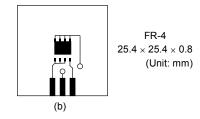


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



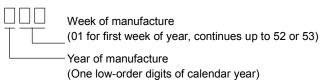


Note 3:  $V_{DD}=24~V,~T_{ch}=25^{\circ}C$  (initial),  $L=100\,\mu$  H,  $R_{G}=25~\Omega,~I_{AR}=-40~A$ 

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: O on lower left of the marking indicates Pin 1.

Weekly code: (Three digits)



## Electrical Characteristics (Ta = 25°C)

Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-OFF cu	rrent	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μΑ
Drain-source brea	akdown voltago	V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V
Diam-source brea	akdown voltage	V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15	- ±10 10 -30	v	
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain source ON	rociotanos	Pro (ON)	$V_{GS} = -4 \text{ V}, I_D = -20 \text{ A}$	_	9.0	14	mO
Drain-source ON resistance		R <sub>DS</sub> (ON)	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -20 A	_	4.5	6.0	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -20 \text{ A}$	30 60 —		_	S
Input capacitance	÷	C <sub>iss</sub>			4600	_	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		850	_	pF
Output capacitan	itput capacitance				980	_	
F	Rise time	t <sub>r</sub>	Vcs 0 V ] [ I <sub>D</sub> = -20A	_	10	_	
	Turn-ON time	t <sub>on</sub>	V <sub>GS</sub> <sub>-10</sub> V   I <sub>D</sub> = -20A   V <sub>GS</sub> <sub>-10</sub> V <sub>OUT</sub>   C <sub>G</sub> V <sub>OU</sub>	_	20	_	
Switching time	Fall time	t <sub>f</sub>	R = 0	_	5 — — — — — — — — — — — — — — — — — — —	_	ns
	Turn-OFF time	t <sub>off</sub>	$V_{DD} \simeq -15 \text{ V}$ Duty $\leq$ 1%, $t_W = 10 \mu\text{s}$		220	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -24 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} = -40 \text{ A}$		109	_	nC
Gate-source charge 1		Q <sub>gs1</sub>		_	24	_	
Gate-source charge 1  Gate-drain ("miller") charge		Q <sub>gd</sub>		_	25	_	

## Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	_	_	_	-120	Α
Forward voltage (diode)			V <sub>DSF</sub>	$I_{DR} = -40 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

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